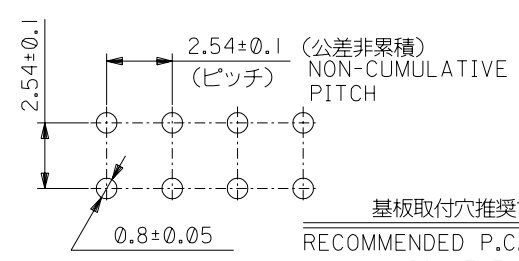
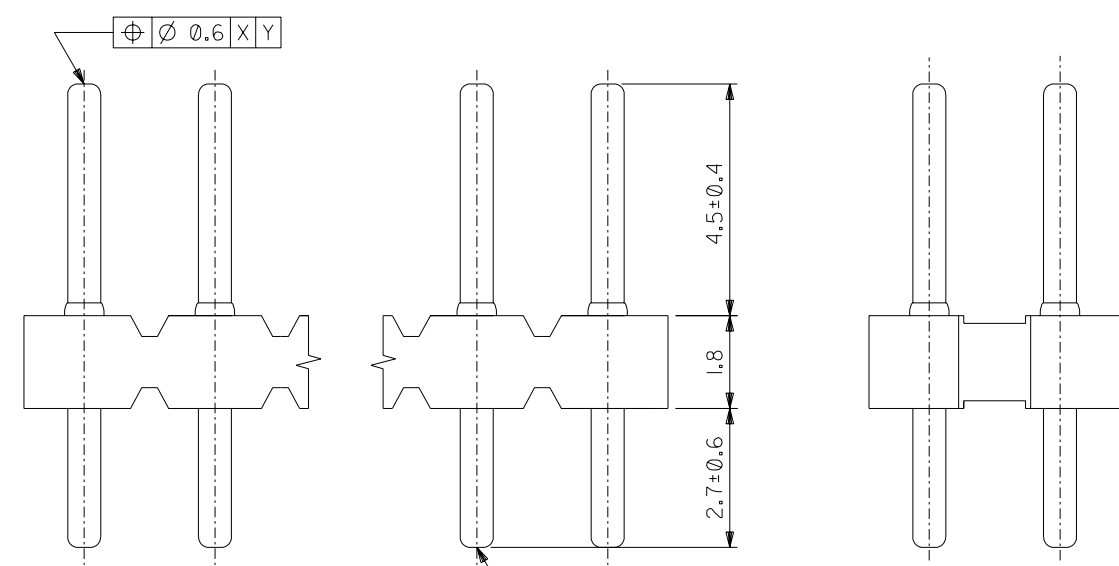
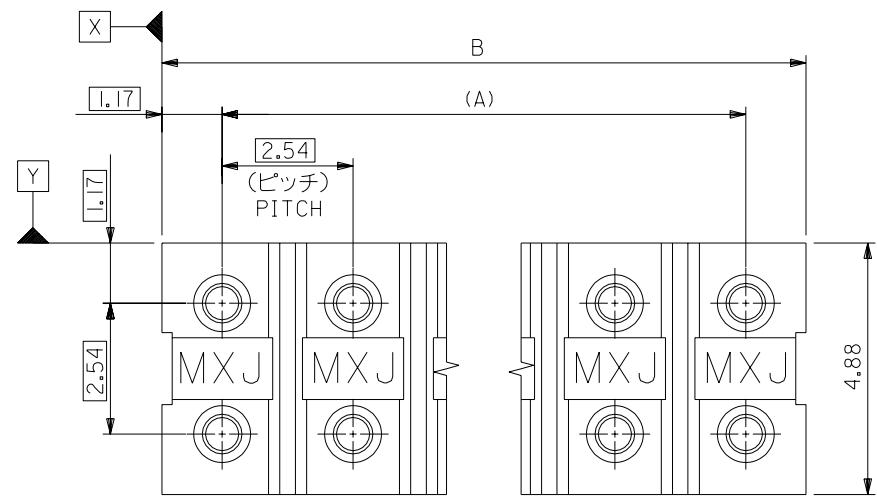


ENG. NO. SD-5547-NA  
EDP NO. #

MM DIMENSIONS IN METRIC DO NOT SCALE DRAWING

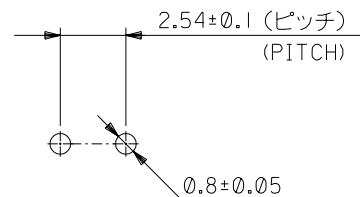
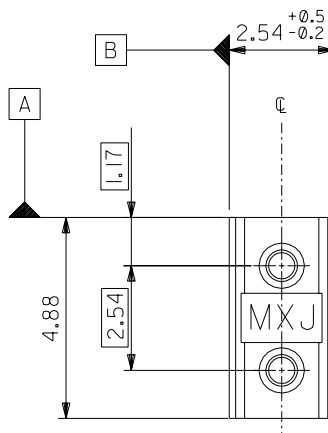
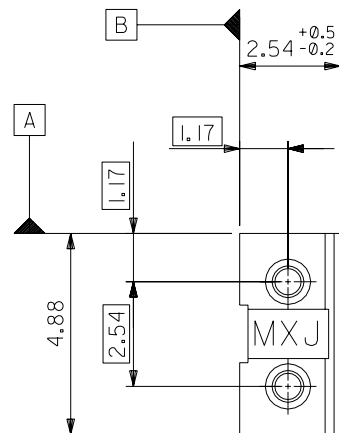


注記:  
NOTES

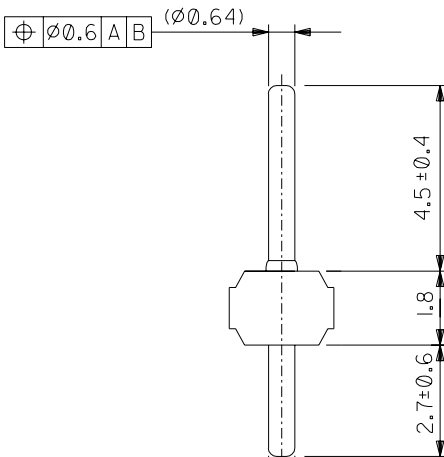
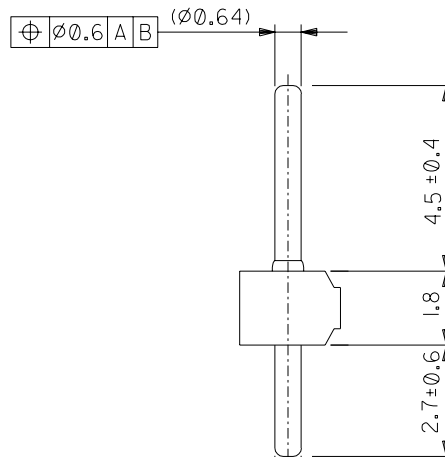
1. 材料  
MATERIAL  
ピン : 黄銅  $\phi 0.64$   
PIN : BRASS  $\phi 0.64$   
ウェハー : ガラス15%入りP.B.T. UL94V-0、黒  
WAFER : P.B.T. G.F.15% UL94V-0, BLACK
2. メッキ仕様  
PLATING  
錫メッキ  
Sn PLATING.
3. 2極は5547-NAを切断加工したものです。  
2 CIRCUITS TO BE MADE BY CUTTING  
5547-NA.

42.98	40.64	5547-34A	34
40.44	38.10	5547-32A	32
37.90	35.56	5547-30A	30
35.36	33.02	5547-28A	28
32.82	30.48	5547-26A	26
30.28	27.94	5547-24A	24
27.74	25.40	5547-22A	22
25.20	22.86	5547-20A	20
22.66	20.32	5547-18A	18
20.12	17.78	5547-16A	16
17.58	15.24	5547-14A	14
15.04	12.70	5547-12A	12
12.50	10.16	5547-10A	10
9.96	7.62	5547-08A	8
7.42	5.08	5547-06A	6
4.48	2.54	5547-04A	4
2.54 $^{+0.5}_{-0.2}$	—	5547-02A	2
B	(A)	ENG. No.	CKT.

角度 ANGLE	$\pm 3^\circ$	材料 MATERIAL	注記参照 SEE NOTES	MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社 EDP. NO. # ENG. NO. (SHEET 1 OF 2) REV B SD-5547-NA TITLE 名称 2.54 DUAL ROW MICRO SHUNT WAFER ASS'Y
30以上 OVER	$\pm 0.3$	仕上げ FINISH	注記参照 SEE NOTES	
10以上 OVER 30未満 UNDER	$\pm 0.25$	適用電線範囲 WIRE RANGE	—	
10未満 UNDER	$\pm 0.2$	被覆外径 INS. RANGE	—	
一般公差 UNIT:mm GENERAL TOLERANCES	REVISION RECORD	DRAWN BY	CHK'D BY	記号 TR 変更内容 REVISION RECORD 日付 DATE APP'D BY 尺度 SCALE 10-1



基板取付穴推奨寸法  
RECOMMENDED P.C.B. LAYOUT  
(SCALE: 5-1)



TYPE I

TYPE II

材料 MATERIAL		注記参照 SEE NOTES		molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
仕上げ FINISH		注記参照 SEE NOTES		REVISE ONLY ON CAD SYSTEM	
適用電線範囲 WIRE RANGE		—		TITLE 名称	
被覆外径 INS. RANGE		—		2.54 DUAL ROW MICRO SHUNT WAFER ASS'Y	
DRAWN BY '96/9/3		CHK'D BY '96/9/3		DWG. NO. (SHEET 2 OF 2) REV	
DR. M.S.		DATE		SD-5547-NA B	
APP'D BY		尺度 SCALE 8-1			
SHEET 1 OF 2 参照 SEE SHEET 1 OF 2 (JD7026)					
記号 LTR		変更内容 REVISION RECORD			
DR. CHK.		DATE			
角度 ANGLE		±3°			
30 以上 OVER		±0.3			
10 以上 OVER 30 未満 UNDER		±0.25			
10 未満 UNDER		±0.2			
一般公差 GENERAL TOLERANCES					